Erratum

Comparison of Impact Toughness and Fracture Morphologies Between Pb-Containing and Pb-Free Solder Joints Subject to the Charpy Impact Test

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In the above mentioned article, reference #4 in the reference list is incorrect. The correct reference is: E.F. De Monlevade and W. Peng, *J. Electron. Mater.* 36, 783 (2007).